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DA2DF62

Silicon epitaxial planar type

For high frequency rectification

Marking Symbol : DA2DF62

Package Code : TO-220D-B1

Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	VRRM	600	V
Non-repetitive peak reverse voltage	VRSM	600	V
Forward current Ta = 25 °C	IF(AV)	10	A
Non-repetitive peak forward surge current *	IFSM	40	A
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-40 to +150	°C

Note: 1. *1 50 Hz sine wave 1cycle(Non-repetitive peak current)

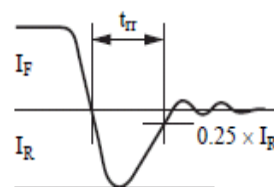
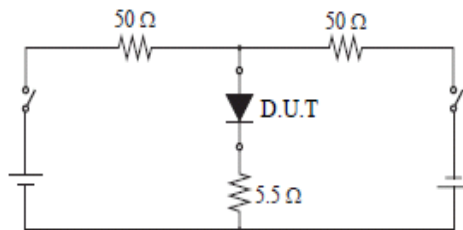
Electrical Characteristics Ta = 25 °C±3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 10 A		1.4	1.7	V
Reverse current	IRRM	VRRM = 600 V			10	μA
Reverse recovery time *1	trr	IF = 0.5 A, VR = 1.0 A Irr = 0.25 A		25	40	ns
Thermal resistance	Rth(j-c)				4.0	°C / W
Thermal resistance	Rth(j-a)				63	°C / W

Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 10 MHz

3. *1 R-load trr test circuit



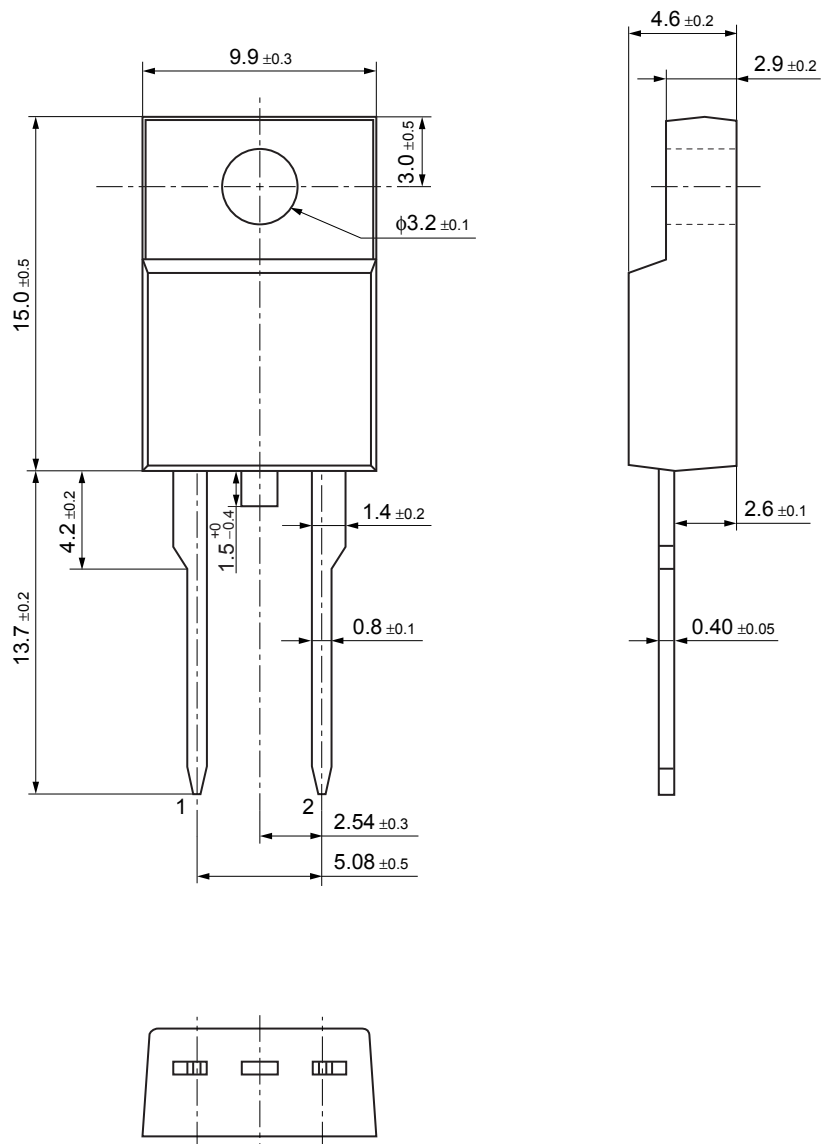
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Magazine 50 pcs

2009.10.28	2010.8.31	
Prepared	Revised	

TO-220D-B1

Unit: mm



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